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# Standard Specification for Electrodeposited Coatings of Palladium- Cobalt Alloy for Engineering Use<sup>1</sup>

This standard is issued under the fixed designation B984; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reappraisal. A superscript epsilon ( $\epsilon$ ) indicates an editorial change since the last revision or reappraisal.

## 1. Scope

1.1 This specification covers requirements for electrodeposited palladium-cobalt alloy coatings containing approximately 80% of palladium and 20% of cobalt. Composite coatings consisting of palladium-cobalt with a thin gold overplate for applications involving electrical contacts are also covered. Palladium and palladium-cobalt remain competitive finishes for high reliability applications.

1.2 *Properties*—Palladium is the lightest and least noble of the platinum group metals (1)<sup>2</sup>. It has the density of 12 gm per cubic centimeter, specific gravity of 12.0, that is substantially lower than the density of gold, 19.29 gm per cubic centimeter, specific gravity 19.3, and platinum 21.48 gm per cubic centimeter, specific gravity 21.5. The density of cobalt on the other hand is even less than palladium. It is only 8.69 gm per cubic centimeter, specific gravity 8.7. This yields a greater volume or thickness of coating and, consequently, some saving of metal weight and reduced cost. Palladium-cobalt coated surface provides a hard surface finish (ASTM E18) thus decreasing wear and increasing durability. Palladium-cobalt coated surface also has very low coefficient of friction 0.43 compared to hard gold 0.60 thus providing lower mating and unmating forces for electrical contacts (1)<sup>2</sup>. Palladium-cobalt has smaller grain size (ASTM E112), 50 – 150 Angstroms, compared to Hard Gold 200 – 250 Angstroms (1)<sup>2</sup>. 5 – 15 nanometer, compared to hard gold 20 – 25 nanometer (1)<sup>2</sup>. Palladium-cobalt has low porosity (ASTM B799) 0.2 porosity index compared to hard gold 3.7 porosity index (1)<sup>2</sup>. Palladium-cobalt coated surface has higher ductility (ASTM B489) 3-7 than that of hard gold <3 (1)<sup>2</sup>. The palladium-cobalt coated surface is also thermally more stable 395°C than hard gold 150°C, and silver 170°C. The following Table 1 compares the hardness range of electrodeposited palladium-cobalt with other electrodeposited noble metals and alloys (3,4).<sup>2</sup>

<sup>1</sup> This specification is under the jurisdiction of ASTM Committee B08 on Metallic and Inorganic Coatings and is the direct responsibility of Subcommittee B08.04 on Precious Metal Coatings.

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<sup>2</sup> The boldface numbers in parentheses refer to the list of references at the end of this specification.

TABLE 1 - Hardness of Noble Metals

	Approximate Hardness (HK <sub>25</sub> )
Gold	50–250
Palladium	75–600
Platinum	150–550
Palladium-Nickel	300–650
Palladium-Cobalt	500–650
Rhodium	750–1100
Ruthenium	600–1300

1.3 *Units*—The values stated in SI units are to be regarded as standard. No other units of measurement are included in this standard.

1.4 *This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use. Some specific hazards statements are given in Section 7 on Hazards.*

## 2. Referenced Documents

2.1 *ASTM Standards*:<sup>3</sup>

- B183 Practice for Preparation of Low-Carbon Steel for Electroplating
- B242 Guide for Preparation of High-Carbon Steel for Electroplating
- B254 Practice for Preparation of and Electroplating on Stainless Steel
- B281 Practice for Preparation of Copper and Copper-Base Alloys for Electroplating and Conversion Coatings
- B322 Guide for Cleaning Metals Prior to Electroplating
- B343 Practice for Preparation of Nickel for Electroplating with Nickel
- B374 Terminology Relating to Electroplating
- B481 Practice for Preparation of Titanium and Titanium Alloys for Electroplating
- B482 Practice for Preparation of Tungsten and Tungsten Alloys for Electroplating
- B487 Test Method for Measurement of Metal and Oxide Coating Thickness by Microscopical Examination of Cross Section

<sup>3</sup> For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

- [B488](#) Specification for Electrodeposited Coatings of Gold for Engineering Uses
- [B489](#) Practice for Bend Test for Ductility of Electrodeposited and Autocatalytically Deposited Metal Coatings on Metals
- [B499](#) Test Method for Measurement of Coating Thicknesses by the Magnetic Method: Nonmagnetic Coatings on Magnetic Basis Metals
- [B507](#) Practice for Design of Articles to Be Electroplated on Racks
- [B542](#) Terminology Relating to Electrical Contacts and Their Use
- [B558](#) Practice for Preparation of Nickel Alloys for Electroplating
- [B567](#) Test Method for Measurement of Coating Thickness by the Beta Backscatter Method
- [B568](#) Test Method for Measurement of Coating Thickness by X-Ray Spectrometry
- [B571](#) Practice for Qualitative Adhesion Testing of Metallic Coatings
- [B602](#) Test Method for Attribute Sampling of Metallic and Inorganic Coatings
- [B679](#) Specification for Electrodeposited Coatings of Palladium for Engineering Use
- [B689](#) Specification for Electroplated Engineering Nickel Coatings
- [B697](#) Guide for Selection of Sampling Plans for Inspection of Electrodeposited Metallic and Inorganic Coatings
- [B741](#) Test Method for Porosity In Gold Coatings On Metal Substrates By Paper Electrography (Withdrawn 2005)<sup>4</sup>
- [B748](#) Test Method for Measurement of Thickness of Metallic Coatings by Measurement of Cross Section with a Scanning Electron Microscope
- [B762](#) Test Method of Variables Sampling of Metallic and Inorganic Coatings
- [B765](#) Guide for Selection of Porosity and Gross Defect Tests for Electrodeposits and Related Metallic Coatings
- [B799](#) Test Method for Porosity in Gold and Palladium Coatings by Sulfurous Acid/Sulfur-Dioxide Vapor
- [B809](#) Test Method for Porosity in Metallic Coatings by Humid Sulfur Vapor (“Flowers-of-Sulfur”)
- [D1125](#) Test Methods for Electrical Conductivity and Resistivity of Water
- [D3951](#) Practice for Commercial Packaging
- [E18](#) Test Methods for Rockwell Hardness of Metallic Materials
- [E112](#) Test Methods for Determining Average Grain Size

### 3. Terminology

3.1 *Definitions*—Many terms used in this specification are defined in Terminology [B374](#) or [B542](#).

3.2 *Definitions of Terms Specific to This Standard:*

3.2.1 *underplating, n*—a metallic coating layer between the basis metal or substrate and the topmost metallic coating. The

thickness of underplating is usually greater than 1  $\mu\text{m}$ . For high energy electrical contact the thickness may be 2.0 – 4.0  $\mu\text{m}$ .

3.2.2 *significant surfaces, n*—defined as those normally visible (directly or by reflector) or essential to the serviceability or function of the article. Can be the source of corrosion products or tarnish films that interfere with the function or desirable appearance of the article. The significant surfaces shall be indicated on the drawings of the parts or by the provision of suitable marked samples.

### 4. Classification

4.1 Orders for articles to be plated in accordance with this specification shall specify the plating system, indicating the basis metal, the thickness of the underplatings, the thickness of the palladium-cobalt coating, and the grade of the gold overplating according to [Table 2](#) and [Table 3](#).

### 5. Ordering Information

5.1 In order to make the application of this standard complete, the purchaser needs to supply the following information to the seller in the purchase order or other governing document:

5.1.1 The name, designation, and date of issue of this standard.

5.1.2 The coating system including basis metal, thickness class and gold overplate grade (see [4.1](#) and [Table 1](#) and [Table 2](#)).

5.1.3 Presence, type, and thickness of underplating (see [3.2.1](#)).

5.1.4 Significant surfaces shall be defined (see [3.2.2](#)).

5.1.5 Requirements, if any, for porosity testing (see [9.5](#)):

5.1.6 Requirement, if any, for bend ductility testing (see [9.6](#)):

5.1.7 Sampling plan employed (see [Section 8](#)), and

5.1.8 Requirement, if any, for surface coating cleanliness (absence of residual salts). See [Appendix X3](#).

### 6. Materials and Manufacture

6.1 Any process that provides an electrodeposit capable of meeting the specified requirements will be acceptable.

6.2 *Substrate:*

6.2.1 The surface condition of the basis metal should be specified and should meet this specification prior to the plating of the parts.

**TABLE 2 Thickness Class<sup>A</sup>**

Thickness Class	Minimum Thickness of Pd-Co ( $\mu\text{m}$ )
0.08	0.08
0.15	0.15
0.25	0.25
0.50	0.50
0.75	0.75
1.00	1.00
1.25	1.25
1.5	1.5
2.5	2.5
3.0	3.0
5.0	5.0

<sup>4</sup> The last approved version of this historical standard is referenced on [www.astm.org](http://www.astm.org).

<sup>A</sup> See [X4.1](#) for specific applications of the various thickness classes.

**TABLE 3 Gold Overplate<sup>A</sup>**

Grade	Type	MIL-G-45204	Hardness (Code)	Thickness Range
1	1 (99.9 % Au min)	III	90 HK <sub>25</sub> max (A)	0.05-0.12 μm
2	2 (99.7 % Au min)	I	130-200 HK <sub>25</sub> (C)	0.05-0.25 μm

<sup>A</sup>See Specification B488 and Appendix Appendix X1.

6.2.2 Defects in the surface of the basis metal, such as scratches, porosity, pits, inclusions, roll and die marks, laps, cracks, burrs, cold shuts, and roughness may adversely affect the appearance and performance of the deposit, despite the observance of the best plating practice. Any such defects on significant surfaces should be brought to the attention of the supplier and the purchaser (See Note 1).

6.2.3 Proper preparatory procedures and thorough cleaning of the basis metal are essential for satisfactory adhesion and performance of these coatings. The surface must be chemically clean and continuously conductive, that is, without inclusions or other contaminants. The coatings must be smooth and as free of scratches, gouges, nicks, and similar imperfections as possible.

6.2.4 The base materials are to be cleaned and prepared as necessary to ensure good Pd-Co plating. The base material preparation may be accomplished in accordance with Practices B183, B254, B281, B322, B343, B481, B482, and B558, and Guide B242.

NOTE 1—A metal finisher can often remove defects through special treatments such as grinding, polishing, abrasive blasting, chemical treatments, and electropolishing. However, these may not be normal in the treatment steps preceding the plating, and a special agreement is indicated.

6.3 Apply the coating after all basis metal preparatory treatments and mechanical operations on significant surfaces have been completed.

#### 6.4 Racking:

6.4.1 Position parts to allow free circulation of solution over all surfaces (ASTM B507). The location of rack or wire marks in the coating should be agreed upon between the purchaser and supplier.

#### 6.5 Plating Process:

6.5.1 *Nickel Underplating*—The nickel underplating (ASTM B689) must be applied before the palladium-cobalt alloy plating when the product is made from copper or copper alloy. Nickel underplatings are also applied for other reasons. See Appendix X2.

6.5.2 *Palladium-Cobalt Overplating*—The electrodeposition process produces mechanically stable Pd-Co films at current densities from less than 50 mA/cm<sup>2</sup> to greater than 700 mA/cm<sup>2</sup>. It can produce alloys of 10 to 30 percent Cobalt content. Any desired composition (for example, 20% Co) can be maintained within ±5 percent over a wide range of operating conditions and bath aging.

6.5.3 *Plating*—Good practice calls for the work to be electrically connected when entering the bath. A minimum of 0.5 V is suggested. During electroplating it is extremely important to maintain the voltage, current density, or both beneath the value for hydrogen evolution, if possible.

6.5.4 *Stress Cracking*—Problems associated with the incorporation of hydrogen in the palladium-cobalt, which can lead to stress cracking of the coating, shall be controlled by choosing plating baths and plating conditions that minimize the H/Pd-Co deposition ratio. The presence of stress-induced microcracks that penetrate to the underlying substrate or underplating can be detected with one of the porosity tests specified in 9.5.

6.5.5 *Gold Overplating*—A thin gold overplating after the palladium-cobalt can be applied in an application in which gold plated electrical connectors are mated together in a contact pair. This process is necessary to preserve the performance of the contact surface. See Appendix X1 for other reasons for using a gold overplate.

6.5.6 *Residual Salts*—For rack and barrel plating applications, residual plating salts can be removed from the articles by a clean, hot (50 to 100°C) water rinse. A minimum rinse time of 2.5 min (racks) or 5 min (barrel) is suggested. Best practice calls for a minimum of three dragout rinses and one running rinse with dwell times of 40 s in each station when rack plating and 80 s when barrel plating. Modern high-velocity impingement type rinses can reduce this time to a few seconds. This is particularly useful in automatic reel-to-reel applications where dwell times are significantly reduced. See Appendix Appendix X3.

## 7. Coating Requirements

7.1 *Coating Composition*—The preferred palladium-cobalt alloy composition should be 80% palladium and 20% cobalt; however the palladium (ASTM B679) content should never be less than 70% and the cobalt should never be more than 30%.

7.2 *Appearance*—Palladium-cobalt coatings shall be smooth, uniform and continuous in appearance with no cracks, pits, nodules, blisters, roughness, excessive edge buildup, areas of no plating, burned deposits or any other unwanted visible plating irregularity. The examination should be done with the unaided eye and under 10X magnification.

7.3 *Thickness*—Everywhere on the significant surface (see 5.1.4), the thickness of the palladium coating shall be equal to or exceed the specified thickness. The maximum thickness, however, shall not exceed the drawing tolerance (see Note 3 and Note 2).

NOTE 2—The coating thickness requirement of this specification is a minimum requirement; that is, the coating thickness is required to equal or exceed the specified thickness everywhere on the significant surfaces while conforming to all maximum thickness tolerances given in the engineering drawing. Variation in the coating thickness from point to point on a coated article is an inherent characteristic of electroplating processes. Therefore, the coating thickness will have to exceed the specified value at some points on the significant surfaces to ensure that the thickness equals or exceeds the specified value at all points. Hence, in most cases, the average coating thickness on an article will be greater than the specified value; how much greater is largely determined by the shape of the article (see Practice B507) and the characteristics of the plating process.

NOTE 3—In addition, the average coating thickness on articles will vary from article to article within a production lot. Therefore, if all of the articles in a production lot are to meet the thickness requirement, the average coating thickness for the production lot as a whole will be greater than the average necessary to assure that a single article meets the requirement.